

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5907311

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
AI MASUDA	12/11/2019
AKIRA KOJIMA	12/13/2019
TAKASHI YAMAMOTO	12/12/2019
YOUNG HAN YOON	12/13/2019
AKIHIRO YASUI	12/18/2019
TSUKASA SUENARI	12/19/2019
RECEIVING PARTY DATA	
Name:	HITACHI HIGH-TECHNOLOGIES CORPORATION
Street Address:	24-14, NISHI-SHIMBASHI 1-CHOME
City:	MINATO-KU, TOKYO
State/Country:	JAPAN
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	29713060
CORRESPONDENCE DATA	
Fax Number:	(202)628-8844
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	2026242500
Email:	ehorne@crowell.com, edocket@crowell.com
Correspondent Name:	CROWELL & MORING LLP
Address Line 1:	P.O. BOX 14300
Address Line 4:	WASHINGTON, D.C. 20011-4300
ATTORNEY DOCKET NUMBER:	100929.DA486US
NAME OF SUBMITTER:	LISA A. ADELSON
SIGNATURE:	/Lisa A. Adelson/
DATE SIGNED:	01/13/2020
Total Attachments: 2	
source=DA486US_Assignment#page1.tif	

231950015 us 01

ASSIGNMENT
(譲 渡 証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me, by **Hitachi High-Technologies Corporation**, a corporation organized under the laws of **Japan**, located at **24-14, Nishi-Shimbashi 1-chome, Minato-ku, Tokyo, Japan**, receipt of which is hereby acknowledged, I do hereby sell and assign to said **Hitachi High-Technologies Corporation**, its successors and assigns, all my right, title and interest, in and for the United States of America, in and to

SAMPLE SUPPLY UNIT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, Serial No. **29/713,060**, filed on **November 13, 2019**, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted, to be held and enjoyed by said **Hitachi High-Technologies Corporation**, its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said **Hitachi High-Technologies Corporation**.

Signed on the date(s) indicated aside signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Ai Masuda
Ai MASUDA

12/11/2019

2) Akira Kojima
Akira KOJIMA

12/13/2019

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

3) Takashi Yamamoto 12/12/2019
Takashi YAMAMOTO

4) Young Han Yoon 12/13/2019
Young Han YOON

5) Akihiro Yasui 12/18/2019
Akihiro YASUI

Tsukasa Suenari 12/19/2019
Dec. 19, 2019
6) Tsukasa Suenari 12/18/2019 T.S.
Dec. 19, 2019
Tsukasa SUENARI